

L Number	Hits	Search Text	DB	Time stamp
1	2	("5387314").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 12:46
-	46	(ink-jet or (ink adj jet) or inkjet) and (forming adj2 slots)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/09 11:42
-	20	("5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055" "2001/0003460").PN.	USPAT	2003/12/05 16:50
-	61	(ink-jet or (ink adj jet) or inkjet) and (fill adj2 slot\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 17:53
-	50	(ink-jet or (ink adj jet) or inkjet) and (slot\$1 and (blade or saw\$3)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/05 15:02
-	382	(216/27).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 16:59
-	975	(ink-jet or (ink adj jet) or inkjet) and (slot\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 17:08
-	633	(29/890.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 17:09
-	163	(438/21).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 17:10
-	423	(blade and substrate and (cutting or dicing)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 17:58
-	469	(blade and substrate and (cutting or dicing or etching)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 17:41
-	18	((ink-jet or (ink adj jet) or inkjet or printhead or (print adj head)) and blade and substrate and (cutting or dicing or etching)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/05 17:39
-	235	(blade and substrate and (cut or dice\$1)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 16:40

-	429	(216/17).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 17:43
-	877	(216/52).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 17:51
-	660	(438/113).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 17:53
-	1	("6527965").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 17:57
-	151	(blade and dic\$3 and (etch\$3 or laser)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 18:00
-	162	((blade or saw\$3) and dic\$3 and (etch\$3 or laser)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 18:00
-	314	((blade or saw\$3) and dic\$3 and (etch\$3 or laser)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 18:00
-	61	(blade and dic\$3 and (etch\$3 or laser)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/05 18:01
-	3356	((blade or saw\$3) and (cut\$3 or separat\$3 or dice\$1) and (wafer\$1 or substrate\$1)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 16:54
-	308	((blade or saw\$3) and (cut\$3 or separat\$3 or dice\$1) and (wafer\$1 or substrate\$1)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 16:42
-	86	((blade or saw\$3) and (cut\$3 or separat\$3 or dice\$1) and (wafer\$1 or substrate\$1) and ink).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 17:10
-	4	((grit or sand or media) adj (blast\$3 or drill\$3)) and (cut\$3 or separat\$3 or dice\$1) and (wafer\$1 or substrate\$1) and ink).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 17:13
-	140	((grit or sand or media) adj (blast\$3 or drill\$3)) and ink).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 17:13
-	43	((grit or sand or media) adj (blast\$3 or drill\$3)) and (inkjet or ink-jet or (ink adj jet) or ((ink or feed) near3 slots)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 17:15

-	22	(ink-jet or (ink adj jet) or inkjet) and (saw\$3 with (drill\$3 or laser or blast\$3 or ablat\$3) with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2003/12/08 18:10
-	24	("4504340" "5028937" "5227813" "5248998" "5311218" "5351375" "5359760" "5365645" "5421071" "5485663" "5581861" "5590451" "5598196" "5600357" "5650810" "5688391" "5697144" "5725825" "5758396" "5809646" "5818479" "5820771" "5904892" "5924197").PN.		2003/12/08 17:59
-	4	((("5227813") or ("5028937"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 18:01
-	3	(ink-jet or (ink adj jet) or inkjet) and (saw\$3 with blast\$3 with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 18:13
-	29	((ink-jet or (ink adj jet) or inkjet) and ((feed or ink) adj slots)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 11:47
-	9	(saw\$3{or blade) and ((feed or ink) adj slots).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 10:28
-	3	((ink-jet or (ink adj jet) or inkjet) and ((feed or ink) adj slots)) same (blade or saw\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 11:53
-	92	((ink-jet or (ink adj jet) or inkjet) and ((supply or ink) adj channel\$1)) same (blade or saw\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:10
-	265	((ink-jet or (ink adj jet) or inkjet or printhead or print-head or (print adj head)) and ((supply or ink) adj channel\$1)) same (laser or drill\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:10
-	13	((ink-jet or (ink adj jet) or inkjet or printhead or print-head or (print adj head)) and ((supply or ink) adj channel\$1)) same ((laser or drill\$3) and (blast\$3 or etch\$3) and (saw\$3 or blade))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:00
-	38	((ink-jet or (ink adj jet) or inkjet) and ((supply or ink) adj channel\$1)) with (blade or saw\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:10
-	117	((ink-jet or (ink adj jet) or inkjet or printhead or print-head or (print adj head)) and ((supply or ink) adj channel\$1)) with (laser or drill\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:10
-	13	((ink-jet or (ink adj jet) or inkjet or printhead or print-head or (print adj head)) and ((supply or ink) adj channel\$1)) with (blast\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:23

-	523	((ink-jet or (ink adj jet) or inkjet or printhead or print-head or (print adj head)) and ((supply or ink) adj channel\$1)) with (etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:10
-	554	(438/460).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:26
-	481	(438/462).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:35
-	215	(438/461).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:35
-	73	(438/463).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:35
-	461	((438/460).CCLS.) or ((438/462).CCLS.) and (blade or saw\$3)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 13:01
-	18	((438/460).CCLS.) or ((438/462).CCLS.) and (blade or saw\$3) with (laser or drill\$3) with (etch\$3 or blast\$3)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:55
-	153	((438/460).CCLS.) or ((438/462).CCLS.) and (blade or saw\$3) with ((laser or drill\$3) or (etch\$3 or blast\$3))	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:52
-	39	((438/460).CCLS.) or ((438/462).CCLS.) and (blade or saw\$3) same (laser or drill\$3) same (etch\$3 or blast\$3)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:52
-	801	(451/38).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:55
-	385	(451/48).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:58
-	4	((451/48).CCLS.) and (semiconductor or wafer)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:58
-	72	((451/38).CCLS.) and (semiconductor or wafer)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 12:59
-	280	((438/460).CCLS.) or ((438/462).CCLS.) and (blade or saw\$3) and (\$5side or top or bottom or back\$4).clm.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/09 13:03
-	16	5272114.URPN.	USPÄT	2003/12/09 13:05

-	1519	(ink-jet or (ink adj jet) or inkjet) and (slot\$1 and (blade or saw\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/05 15:02
-	1109	((feed or ink) adj (slot\$1 or channel\$1)) with (laser or drill\$3 or saw\$3 or blade or etch\$3 or mill\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 17:33
-	1	((feed or ink) adj (slot\$1 or channel\$1)) with ((laser or drill\$3) and (saw\$3 or blade) and (etch\$3 or mill\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 10:31
-	130	((feed and ink) with (slot\$1 or channel\$1)) with (laser or drill\$3 or saw\$3 or blade or etch\$3 or mill\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 13:41
-	2	("6271102").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 12:42
-	22	("4015175" "4104697" "4292576" "4312115" "4721977" "4729971" "4814296" "4846032" "4900283" "4985982" "5000811" "5217907" "5219796" "5272114" "5369060" "5477065" "5786266" "5843831" "5858808" "5943591" "5998238" "6124148").PN.	USPAT	2004/02/19 12:42
-	11	((feed and ink) with (slot\$1 or channel\$1)) with (aspect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 13:42
-	55	((feed or ink) with (slot\$1 or channel\$1)) with (aspect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 14:01
-	119	((ink adj jet) or inkjet or ink-jet or printhead) and ((slot\$1 or channel\$1) with (aspect adj ratio))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 14:03
-	19	((ink adj jet) or inkjet or ink-jet or printhead) and ((slot\$1 or channel\$1) with (aspect adj ratio)) and (blade or saw\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 14:02
-	50	((ink adj jet) or inkjet or ink-jet or printhead) and ((slot\$1 or channel\$1) with (aspect adj ratio)) and (blade or saw\$3 or drill\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 14:04
-	30	((ink adj jet) or inkjet or ink-jet or printhead) and ((slot\$1 or channel\$1) with (aspect adj ratio)) and (blade or saw\$3 or drill\$3) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 14:04
-	155	((feed or ink) adj (slot\$1 or channel\$1)) with drill\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/19 17:34

-	44	(ink adj (slot\$1 or channel\$1)) with drill\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 18:05
-	123	(rotary and laser) with drill\$3	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 17:38
-	16	(rotary and laser) with drill\$3 and silicon	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 17:38
-	9	(rotary and laser) adj drill\$3	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 17:39
-	8	(rotary adj drill\$3) with silicon	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 17:39
-	13	(diamond adj (blade or saw)) same ((diamond or rotary) adj drill\$3)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 18:07
-	26	(diamond adj2 (blade or saw)) same ((diamond or rotary) adj2 drill\$3)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 18:07
-	12	(diamond adj2 (blade or saw)) with ((diamond or rotary) adj2 drill\$3)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/19 18:07
-	18	router with saw with slot	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 10:14
-	260	(miter adj saw).ti.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 10:15
-	2	(router and slot and method).ti.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 10:15
-	156	(router same slot).ab.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 10:27
-	71	router with slot\$2 with workpiece	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 10:30
-	4	(router and saw) with slot\$2 with workpiece	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 10:31